

44.(Amended) An electronic component unit, wherein the electronic component is mounted on the board by the electronic component mounting method claimed in claim 1.

45.(Amended) An electronic component mounting apparatus as claimed in claim 11, wherein the apparatus for metallicity bonding the gold bump to the electrode of the board with supersonic waves applied comprises a heating member for effecting heating from the upper surface side of the electronic component or from the board side or from both the electronic component side and the board side, and the heating is effected by the heating member at a time of metallic bonding.

Add the following new claims:

46.(NEW) An electronic mounting method comprising:

mounting an electronic component (1) on a circuit board (4) while aligning in position an electrode of the electronic component (1) and an electrode (5) of the circuit board (4) in a state in which the electrode (2) of the electronic component (1) has a bump (3, 103) with interposition of an anisotropic conductive layer (10) in which an insulating resin mixed with an inorganic filler is mixed with a conductive particle (10a); and subsequently bonding the electronic component to the circuit board by hardening the insulating resin of the anisotropic conductive layer interposed between the electronic component and the circuit board while correcting warp of the board with a pressure force applied to the electronic component against the circuit board by means of a tool (8) and heat applied from the electronic component side or heat applied from the board side or heat applied from both the electronic component side and the board side, so that the electrode of the electronic component is electrically connected with the electrode of the circuit board.

47.(NEW) An electronic component mounting method comprising:

mounting an electronic component (1) on a circuit board (4) while aligning in position an electrode of the electronic component (1) and an electrode (5) of the circuit board (4) with interposition of a solid or semi-solid insulating resin layer (6,

306b) in which an insulating resin (306m) is mixed with an inorganic filler (6f) without leveling a bump (3, 103) owned by the electrode (2) of the electronic component (1); and subsequently bonding the electronic component to the circuit board by hardening the insulating resin interposed between the electronic component and the circuit board while correcting warp of the board with a pressure force applied to the electronic component against the circuit board by means of a tool (8) and heat applied from the electronic component side or heat applied from the board side or heat applied from both the electronic component side and the board side, so that the electrode of the electronic component is electrically connected with the electrode of the circuit board.

48. (NEW) An electronic component mounting method as claimed in claim 1, wherein the inorganic filler is constructed of ceramics of spherical or pulverized silica, alumina, or the like.

49. (NEW) An electronic component unit, wherein the electronic component is mounted on the board by the electronic component mounting method claimed in claim 47.

50.(NEW) An electronic component mounting method as claimed in claim 5, wherein the electronic component (1) has a plurality of electrodes (2), a solid anisotropic conductive film sheet (10) that has a configurational dimension smaller than an outline dimension (OL) defined by joining the plurality of electrodes (2) of the electronic